

Fig. 7

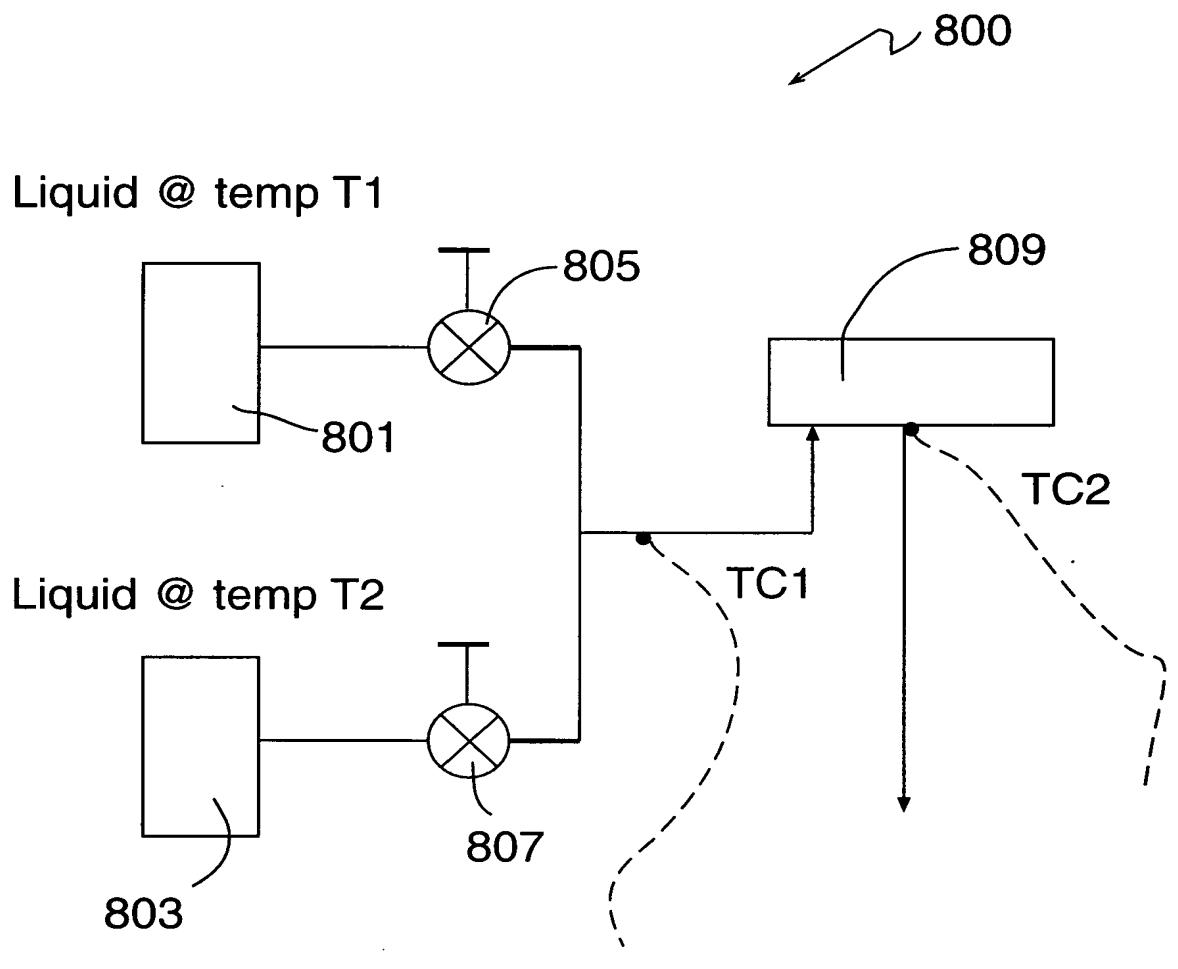
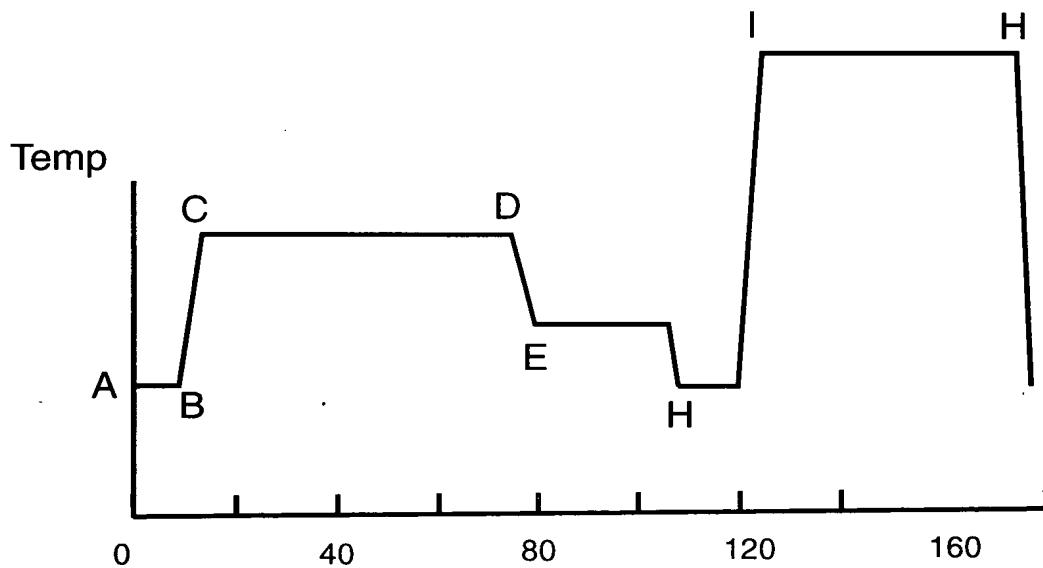
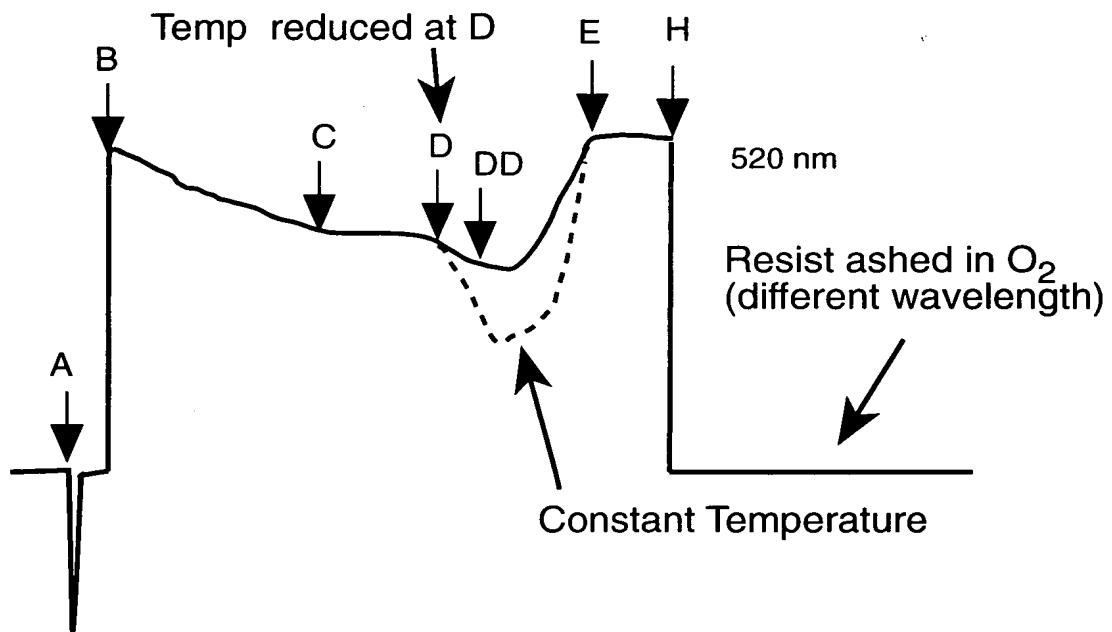


Fig. 8



- A. SF₆ native oxide "breakthrough"
- B. Cl₂ plasma is ignited
- C. WSi_x begins to clear (endpoint)
- D. Polysilicon is exposed
- E. Polysilicon cleared to oxide

- H. Plasma extinguished and O₂ feed gas flow is started
- I. O₂ plasma is started
- J O₂ plasma is extinguished.

Fig. 10

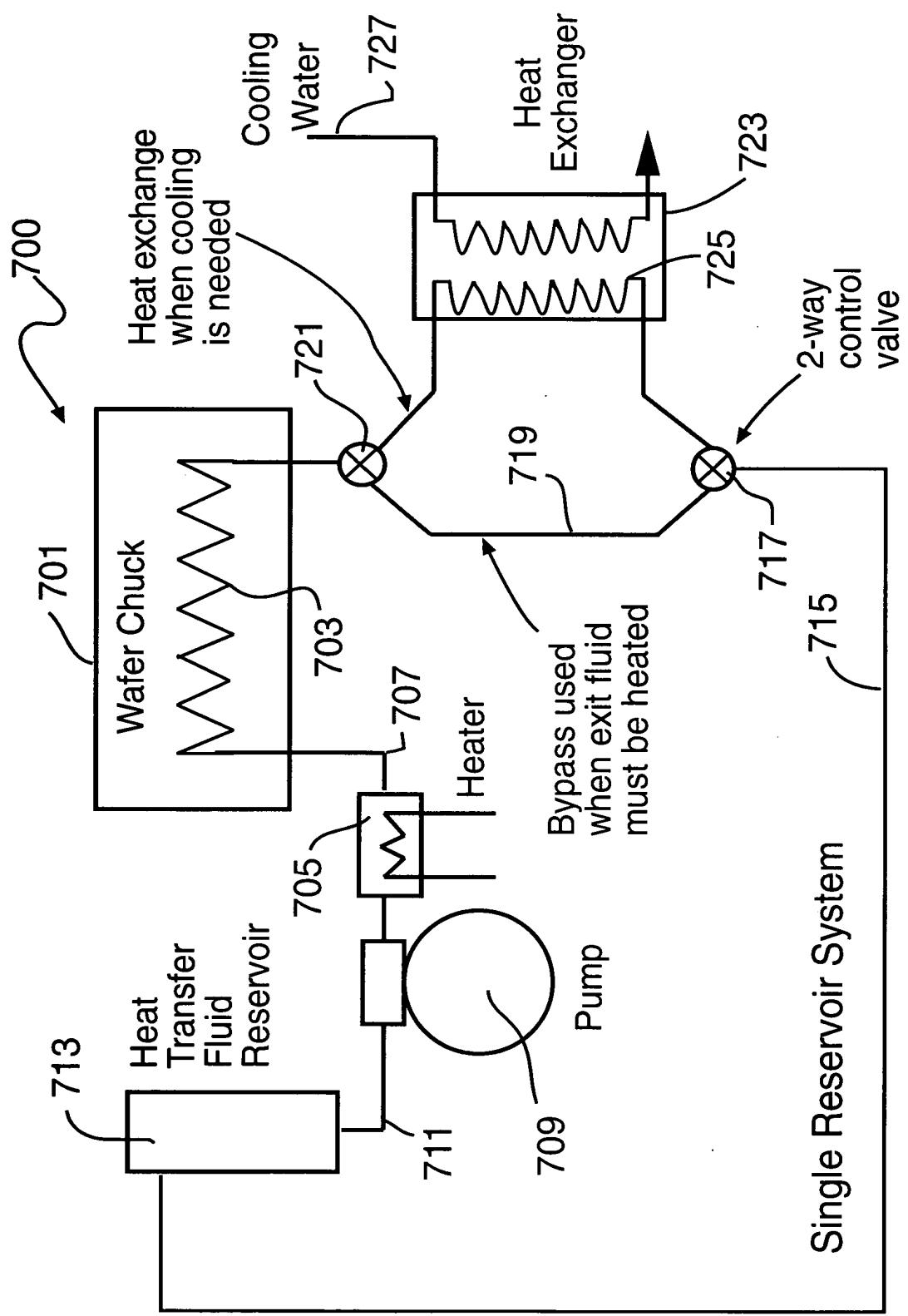


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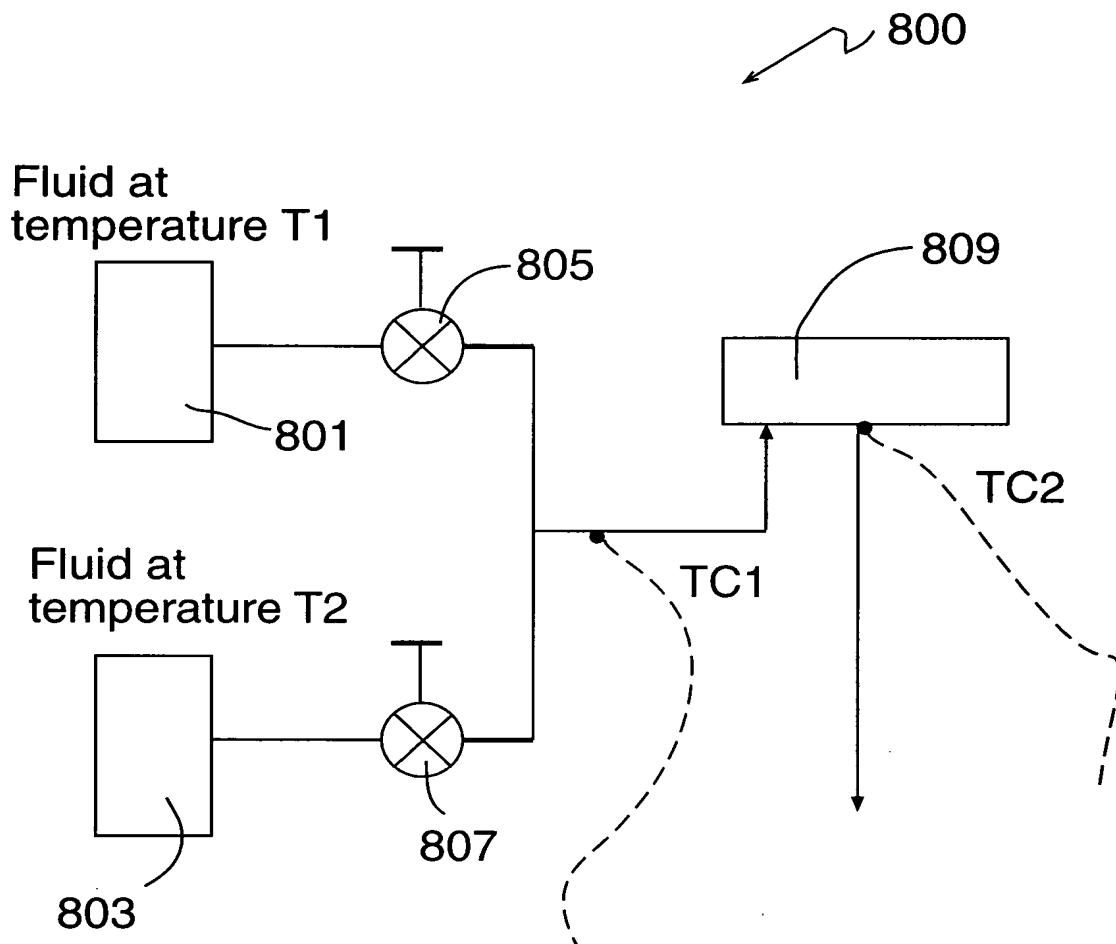
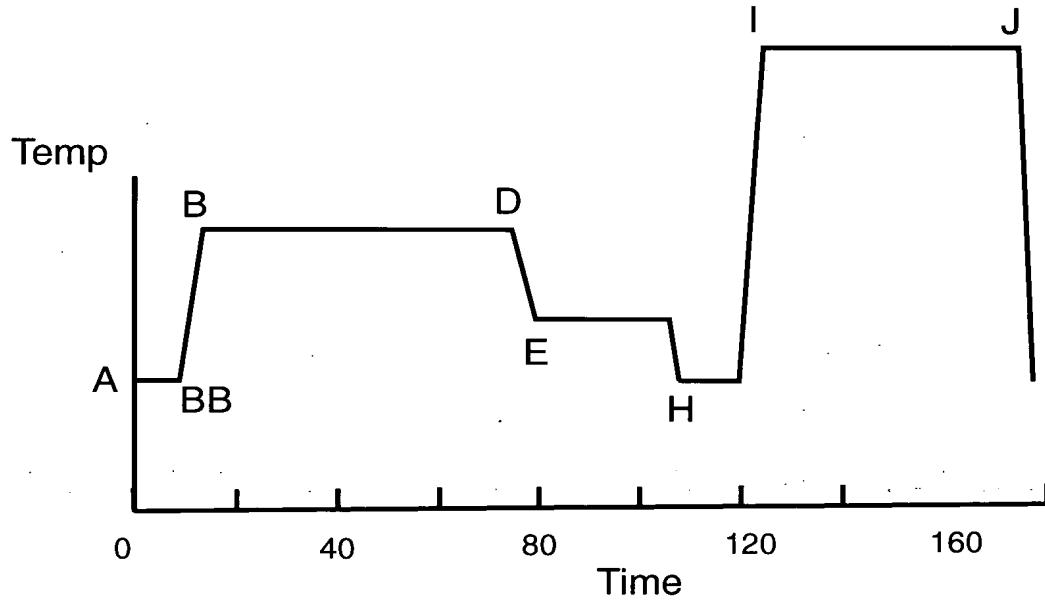
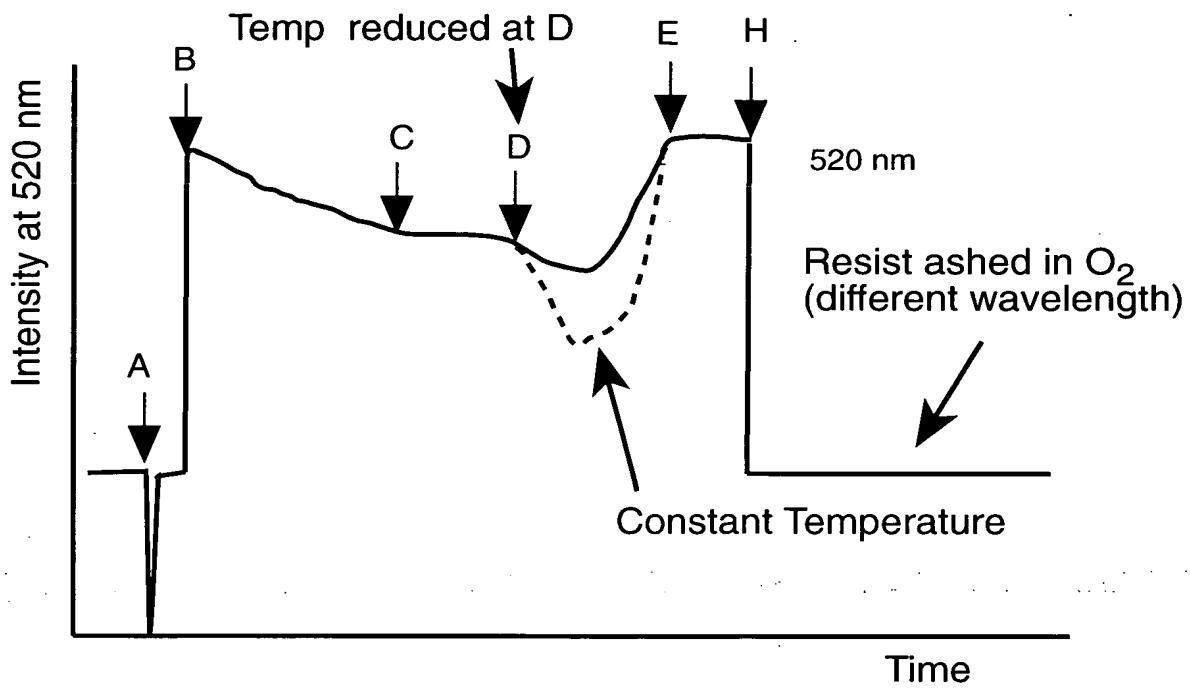


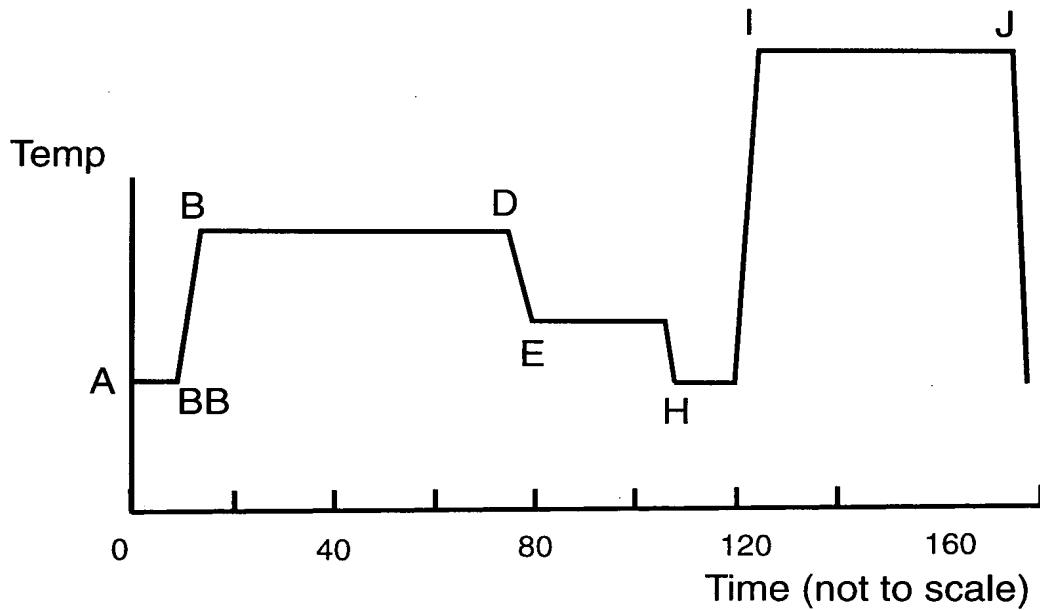
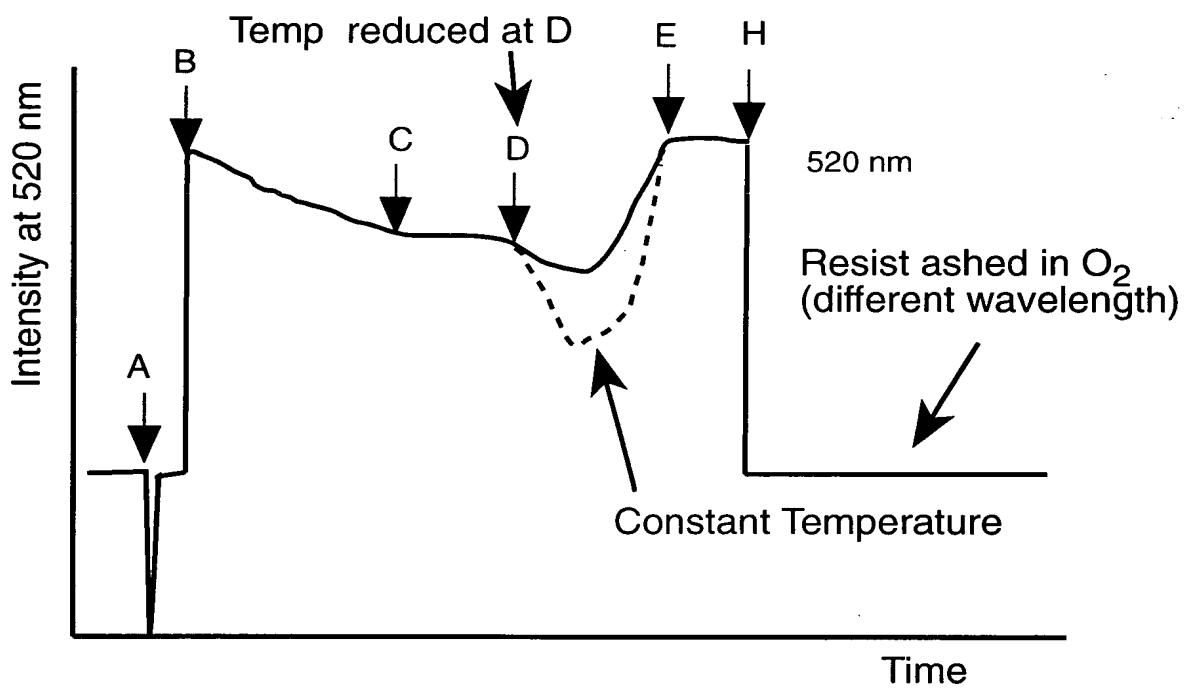
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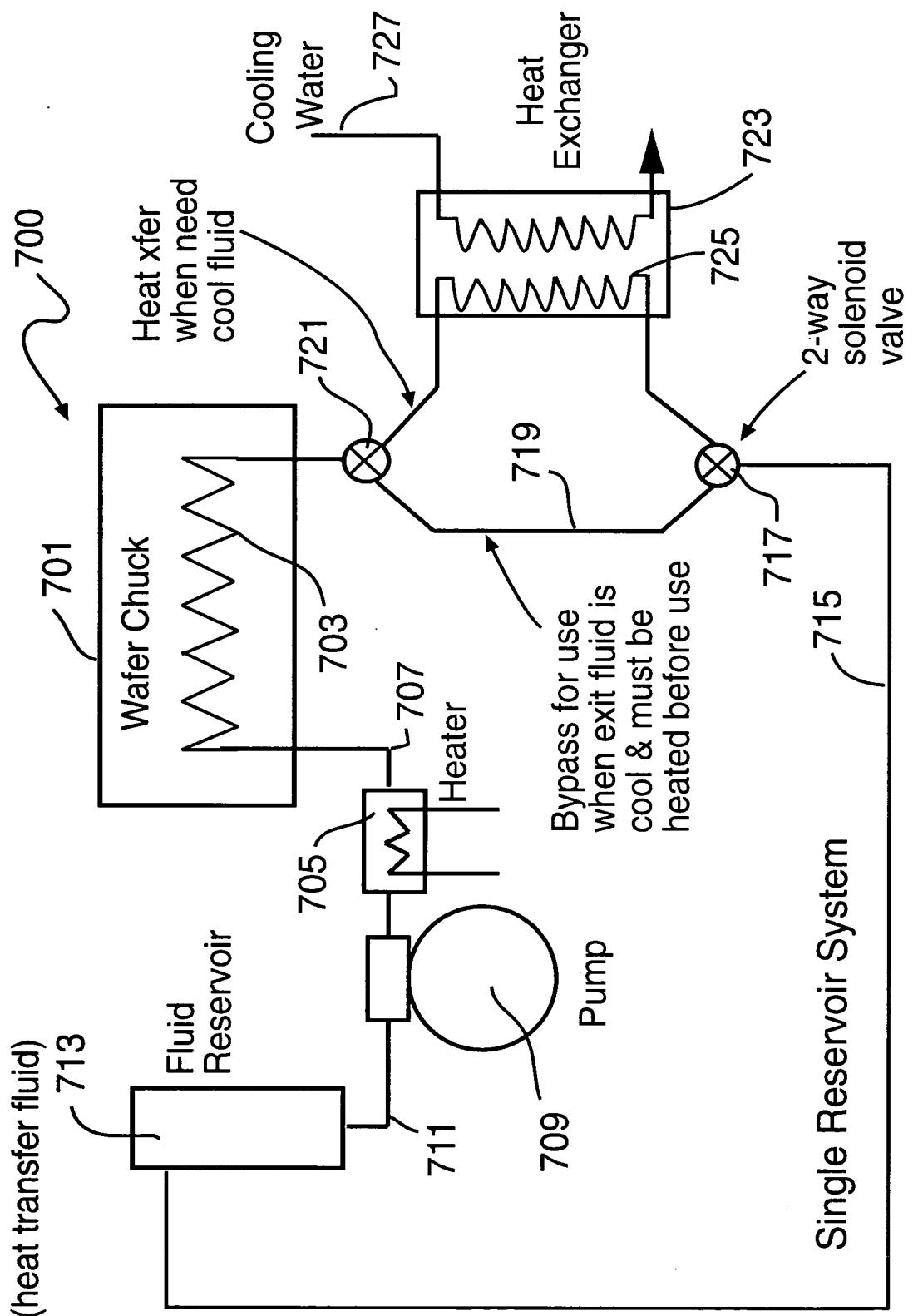


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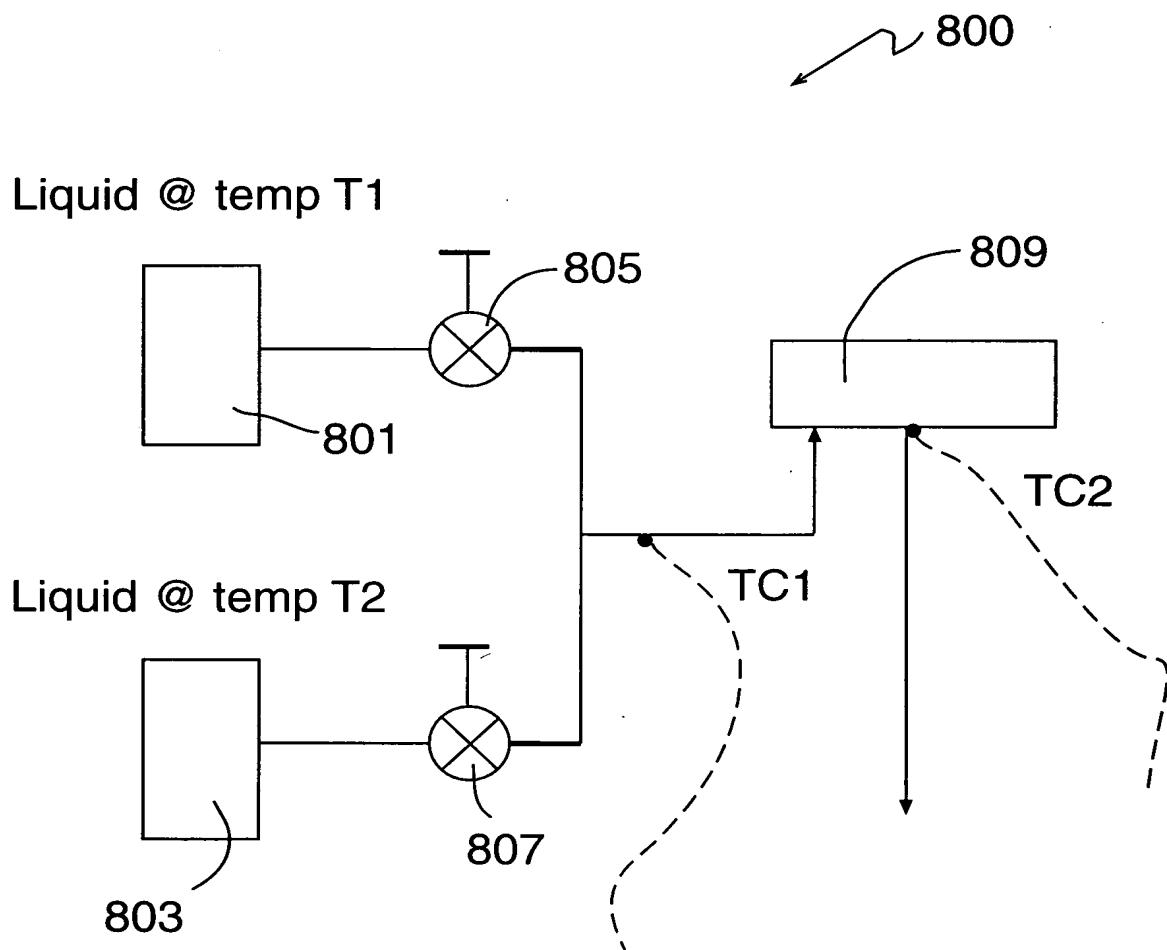
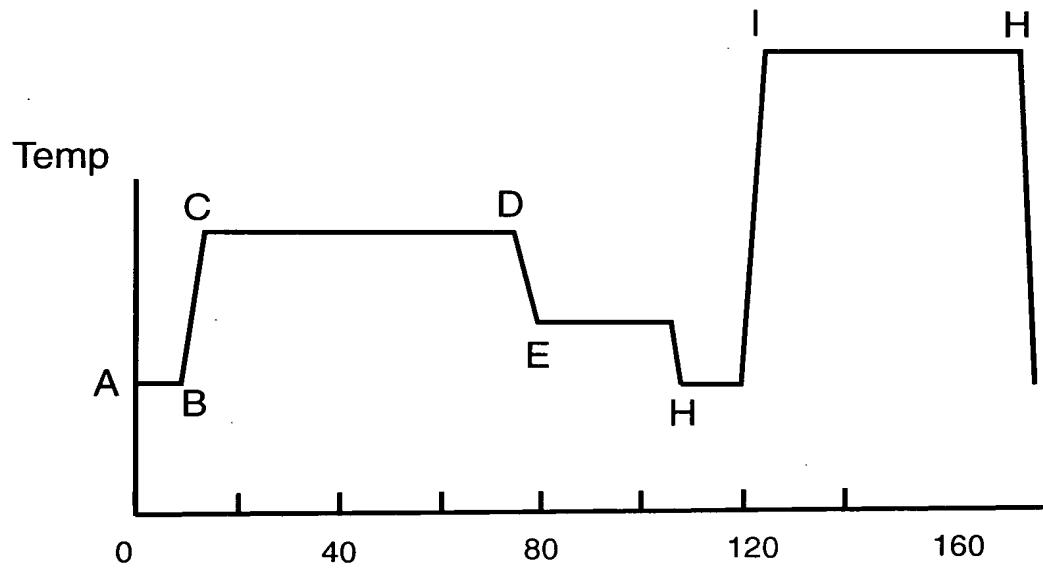
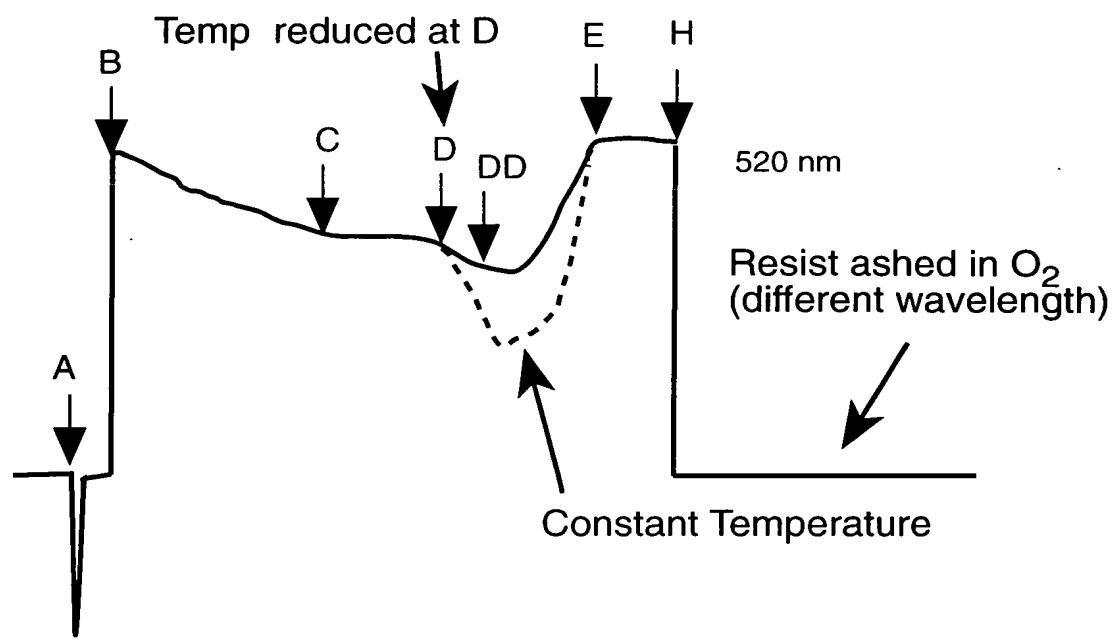


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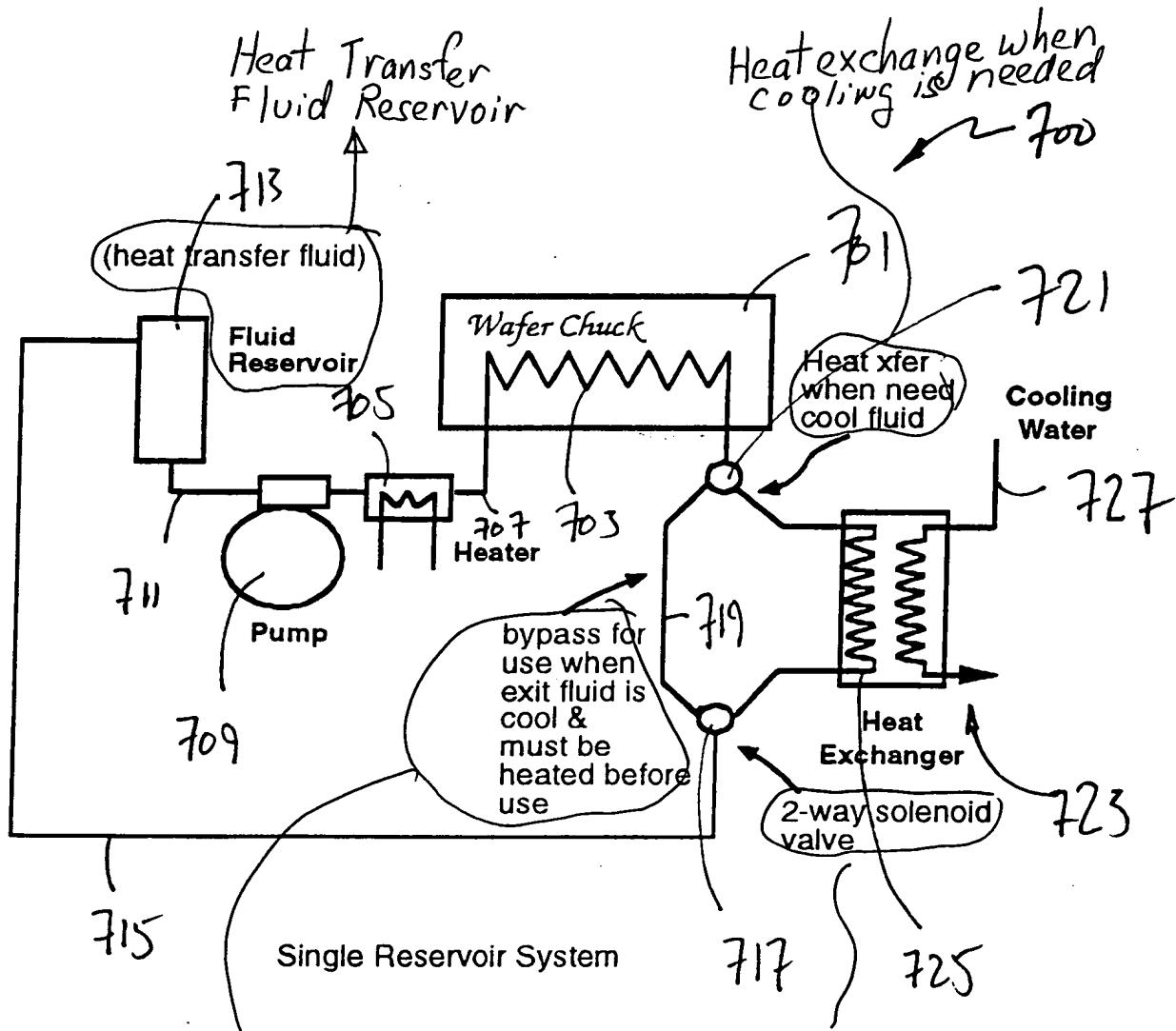


FIG. 7

Bypass used
when exit fluid
must be heated

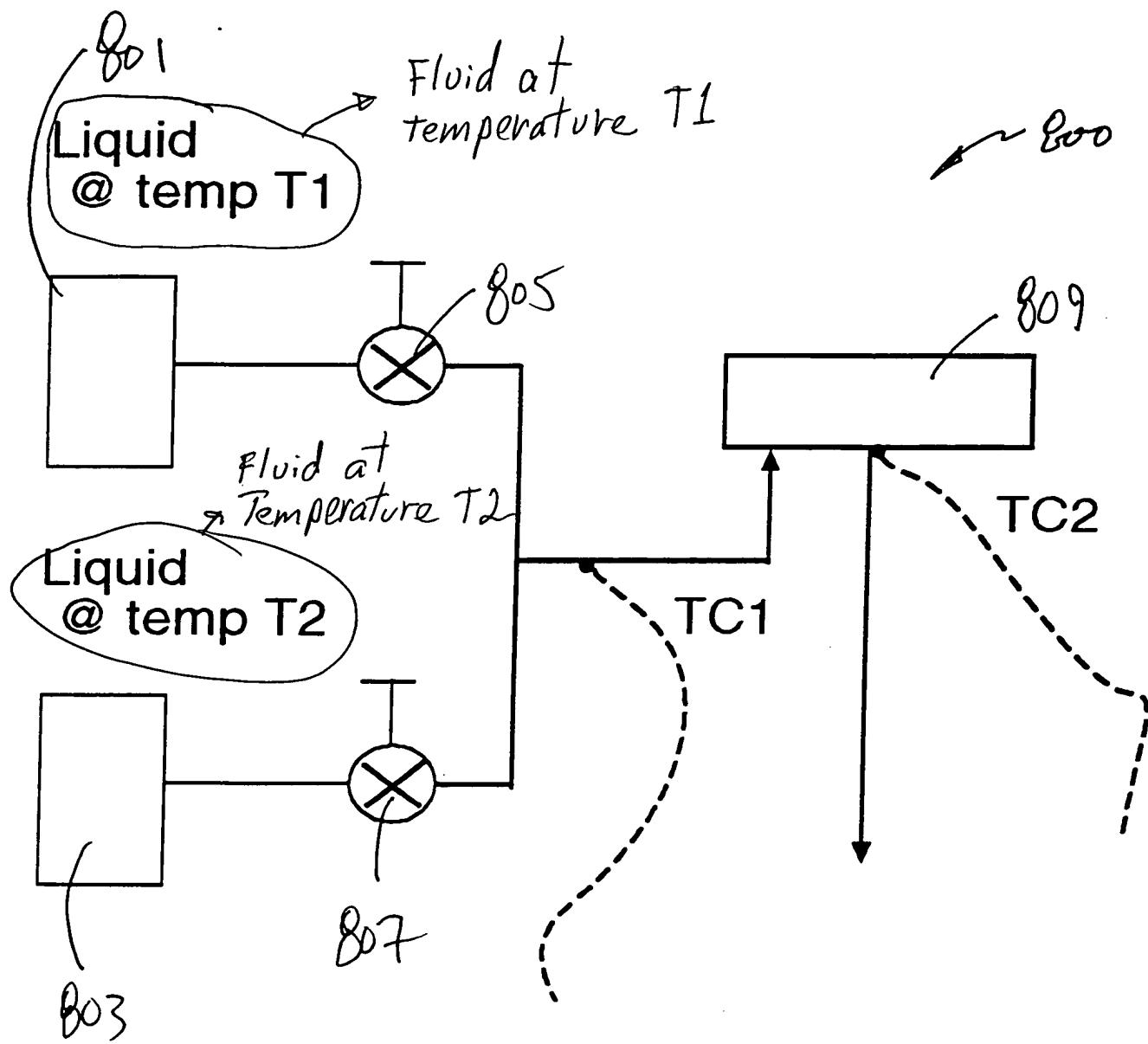
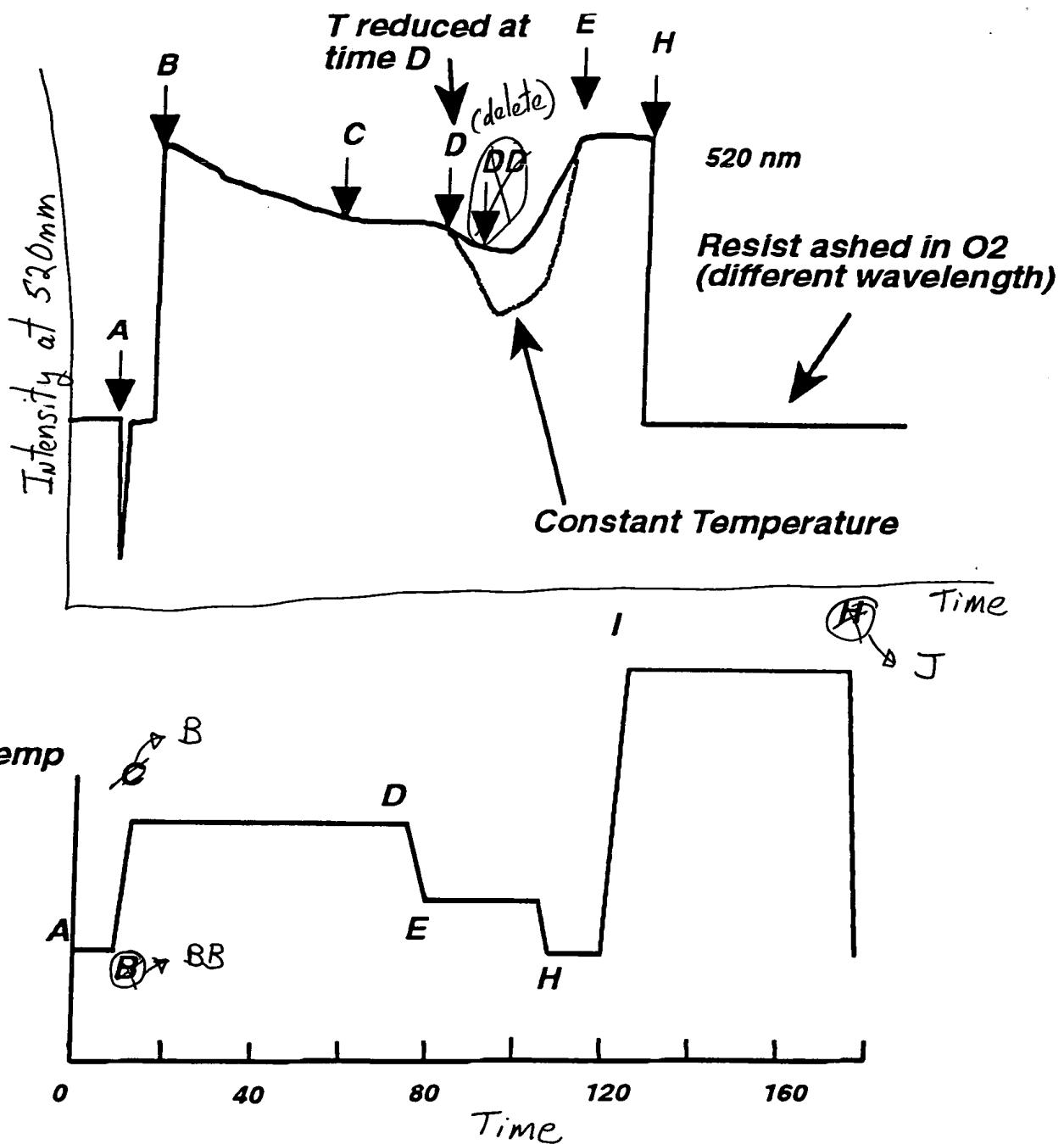


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